Ahmed Sharif

List of Publications by Year
in descending order

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62	1,680	24	40
papers	citations	h-index	g-index

257357

289141

73	73	73	994
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Effect of Areca and Waste Nylon Fiber Hybridization on the Properties of Recycled Polypropylene Composites. Journal of Natural Fibers, 2022, 19, 6625-6637.	1.7	6
2	Enhanced dielectric stability and coercivity of band gap tuned Baâ€"Al Co-doped bismuth ferrite: An experimental and DFT+U investigation. Ceramics International, 2022, 48, 3404-3416.	2.3	12
3	Effects of transition metal (Fe, Co & Ni) doping on structural, electronic and optical properties of CuO: DFTÂ+ÂU study. Chemical Physics, 2021, 545, 111160.	0.9	21
4	Characteristics of eutectic and near-eutectic Znâ€"Al alloys as high-temperature lead-free solders. Journal of Materials Science: Materials in Electronics, 2020, 31, 1691-1702.	1.1	9
5	Effect of Minor Addition of Ni on the Microstructure and Properties of Zn-Based High-Temperature Solder. Journal of Electronic Materials, 2020, 49, 3990-4001.	1.0	2
6	Role of hydrogen co-doping on opto-electronic behaviors of Na-H co-doped zinc oxide: a first principle study. Journal of Physics Communications, 2020, 4, 115002.	0.5	2
7	Evidence of superparamagnetism and improved electrical properties in Ba and Ta co-doped BiFeO3 ceramics. Journal of Alloys and Compounds, 2018, 735, 2584-2596.	2.8	46
8	Characteristics of Znâ€"Sb based high temperature solder alloy. Journal of Materials Science: Materials in Electronics, 2018, 29, 18417-18425.	1.1	4
9	Zn-Based Solders for High Temperature Electronic Application. , 2016, , .		3
10	Structural transition and its effect in La, Zr co-substituted mono-domain BiFeO3. Journal of Applied Physics, 2016, 120, 214106.	1.1	19
11	Mechanical and Thermal Properties of Zn-xMg Solder Alloys. Applied Mechanics and Materials, 2016, 860, 173-178.	0.2	2
12	Correlation of charge defects and morphology with magnetic and electrical properties of Sr and Ta codoped BiFeO3. Journal of Alloys and Compounds, 2016, 688, 1186-1194.	2.8	35
13	Study of off-eutectic Znâ€"xMg high temperature solder alloys. Journal of Materials Science: Materials in Electronics, 2016, 27, 8734-8744.	1.1	14
14	Study on the properties of Znâ€"xNi high temperature solder alloys. Journal of Materials Science: Materials in Electronics, 2016, 27, 3608-3618.	1.1	13
15	Review on advances in nanoscale microscopy in cement research. Micron, 2016, 80, 45-58.	1.1	10
16	Nanocharacterization of interface between natural fiber and polymer matrix: an overview. Composite Interfaces, 2016, 23, 105-123.	1.3	14
17	Structural, dielectric and magnetic properties of Ta-substituted Bi0.8La0.2FeO3 multiferroics. Journal of Alloys and Compounds, 2015, 622, 471-476.	2.8	16
18	Utilization of open pit burned household waste ash â€" a feasibility study in Dhaka. Waste Management and Research, 2014, 32, 397-405.	2.2	3

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19	Customized glass sealant for ceramic substrates for high temperature electronic application. Microelectronics Reliability, 2014, 54, 2905-2910.	0.9	18
20	Effect of micron size Ni particle addition in Snâ€“8Znâ€“3Bi lead-free solder alloy on the microstructure, thermal and mechanical properties. Journal of Alloys and Compounds, 2014, 585, 32-39.	2.8	59
21	Transient liquid phase Ag-based solder technology for high-temperature packaging applications. Journal of Alloys and Compounds, 2014, 587, 365-368.	2.8	72
22	Pb-Free Glass Paste: A Metallization-Free Die-Attachment Solution for High-Temperature Application on Ceramic Substrates. Journal of Electronic Materials, 2013, 42, 2667-2676.	1.0	11
23	Electronic packages for high pressure applications: A dome-shaped cavity design. , 2013, , .		0
24	Ceramic — Ceramic joining using glass frit for high temperature application. , 2012, , .		1
25	Study of thin film metallization adhesion in ceramic multichip module. , 2012, , .		2
26	Influence of SrTiO3 nano-particles on the microstructure and shear strength of Snâ€“Agâ€“Cu solder on Au/Ni metallized Cu pads. Journal of Alloys and Compounds, 2011, 509, 1885-1892.	2.8	66
27	Influence of Ag micro-particle additions on the microstructure, hardness and tensile properties of Snâ€“9Zn binary eutectic solder alloy. Microelectronics Reliability, 2010, 50, 1134-1141.	0.9	46
28	Effect of nano Al2O3 additions on the microstructure, hardness and shear strength of eutectic Snâ€“9Zn solder on Au/Ni metallized Cu pads. Microelectronics Reliability, 2010, 50, 2051-2058.	0.9	36
29	Investigation of small Snâ€“3.5Agâ€“0.5Cu additions on the microstructure and properties of Snâ€“8Znâ€“3Bi solder on Au/Ni/Cu pads. Journal of Alloys and Compounds, 2010, 489, 678-684.	2.8	32
30	The influence of addition of Al nano-particles on the microstructure and shear strength of eutectic Snâ€“Agâ€“Cu solder on Au/Ni metallized Cu pads. Journal of Alloys and Compounds, 2010, 506, 216-223.	2.8	76
31	Effect of small Sn-Ag-Cu additions on structure and properties of Sn-Zn-Bi solder/BGA during as-soldered and as-aged conditions. , 2009, , .		0
32	Synthesis and characterization of indium doped cadmium sulfide nanoribbons. Journal Physics D: Applied Physics, 2009, 42, 035412.	1.3	6
33	Interfacial microstructure and shear strength of Ag nano particle doped Snâ€“9Zn solder in ball grid array packages. Microelectronics Reliability, 2009, 49, 746-753.	0.9	42
34	Effect of Ag micro-particles content on the mechanical strength of the interface formed between Snâ€“Zn binary solder and Au/Ni/Cu bond pads. Microelectronic Engineering, 2009, 86, 2086-2093.	1.1	19
35	Effect of small Snâ€“3.5Agâ€“0.5Cu additions on the structure and properties of Snâ€“9Zn solder in ball grid array packages. Microelectronic Engineering, 2009, 86, 2347-2353.	1.1	29
36	ZnSxSe1â^'x nanowire arrays with tunable optical properties grown on ZnS nanoribbon substrates. Physica E: Low-Dimensional Systems and Nanostructures, 2009, 41, 739-745.	1.3	10

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37	Influence of small amount of Al and Cu on the microstructure, microhardness and tensile properties of Snâ€“9Zn binary eutectic solder alloy. Journal of Alloys and Compounds, 2009, 481, 167-172.	2.8	61
38	Effect of 3 wt.% Bi in Sn-Zn solder on the interfacial reaction with the Au/Ni metallization in microelectronic packaging. , 2008, , .		1
39	A study of Ag micro-particle reinforced Sn-Zn matrix composite solder. , 2008, , .		0
40	Effect of nano Ni additions on the structure and properties of Sn-9Zn and Sn-8Sn-3Bi solder in ball grid array packages. , 2008, , .		3
41	Effect of multiple reflows on mechanical strength of the interface formed between Snâ€“Znâ€“Bi solder and Au/Ni/Cu bond pad. Journal of Materials Research, 2007, 22, 40-45.	1.2	1
42	Investigation of interfacial reactions between Snâ€“Zn solder with electrolytic Ni and electroless Ni(P) metallization. Journal of Alloys and Compounds, 2007, 440, 117-121.	2.8	24
43	Retardation of spalling by the addition of Ag in Snâ€“Znâ€“Bi solder with the Au/Ni metallization. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2007, 445-446, 686-690.	2.6	18
44	Effect of substrate metallization on interfacial reactions and reliability of Snâ€“Znâ€“Bi solder joints. Microelectronic Engineering, 2007, 84, 328-335.	1.1	40
45	Effect of 3 wt.% Bi in Sn-Zn solder on the interfacial reactions with the Au/Ni metallization. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2006, , .	0.0	0
46	Liquid and solid state interfacial reactions of Snâ€“Agâ€“Cu and Snâ€“Inâ€“Agâ€“Cu solders with Niâ€“P under bump metallization. Thin Solid Films, 2006, 504, 431-435.	0.8	30
47	Effect of reaction time on mechanical strength of the interface formed between the Sn-Zn(-Bi) solder and the Au/Ni/Cu bond pad. Journal of Electronic Materials, 2006, 35, 1812-1817.	1.0	13
48	The effect of curing on the performance of ACF bonded chipâ€onâ€flex assemblies after thermal ageing. Soldering and Surface Mount Technology, 2005, 17, 40-48.	0.9	40
49	Comparative Study of the Dissolution Kinetics of Electrolytic Ni and Electroless NiP Layers by Molten Sn3.5Ag Solder Alloy. Journal of Electronic Packaging, Transactions of the ASME, 2005, 127, 365-369.	1.2	4
50	Comparative study of interfacial reactions of Sn-Ag-Cu and Sn-Ag solders on Cu pads during reflow soldering. Journal of Electronic Materials, 2005, 34, 46-52.	1.0	22
51	Effect of volume in interfacial reaction between eutectic Sn-3.5% Ag-0.5% Cu solder and Cu metallization in microelectronic packaging. Journal of Electronic Materials, 2005, 34, 143-149.	1.0	88
52	Interfacial reactions of Sn-3.5% Ag and Sn-3.5% Ag-0.5% Cu solder with electroless Ni/Au metallization during multiple reflow cycles. Journal of Materials Science: Materials in Electronics, 2005, 16, 153-158.	1.1	14
53	Dissolution of electroless Ni metallization by lead-free solder alloys. Journal of Alloys and Compounds, 2005, 388, 75-82.	2.8	48
54	Effect of indium addition in Sn-rich solder on the dissolution of Cu metallization. Journal of Alloys and Compounds, 2005, 390, 67-73.	2.8	76

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55	Interfacial reactions on electrolytic Ni and electroless Ni(P) metallization with Snâ€“Inâ€“Agâ€“Cu solder. Journal of Alloys and Compounds, 2005, 393, 135-140.	2.8	23
56	Effect of 9wt.% in addition to Sn3.5Ag0.5Cu solder on the interfacial reaction with the Au/NiP metallization on Cu pads. Journal of Alloys and Compounds, 2005, 396, 217-223.	2.8	31
57	Interfacial reactions of Snâ€“Cu and Snâ€“Pbâ€“Ag solder with Au/Ni during extended time reflow in ball grid array packages. Journal of Materials Research, 2004, 19, 2897-2904.	1.2	19
58	Dissolution kinetics of BGA Snâ€“Pb and Snâ€“Ag solders with Cu substrates during reflow. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 106, 126-131.	1.7	66
59	Effect of volume in interfacial reaction between eutectic Snâ€“Pb solder and Cu metallization in microelectronic packaging. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 106, 120-125.	1.7	57
60	Interfacial reactions of BGA Snâ€“3.5%Agâ€“0.5%Cu and Snâ€“3.5%Ag solders during high-temperature aging with Ni/Au metallization. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 113, 184-189.	1.7	46
61	Comparative study of the dissolution kinetics of electrolytic Ni and electroless Niâ€“P by the molten Sn3.5Ag0.5Cu solder alloy. Microelectronics Reliability, 2003, 43, 2031-2037.	0.9	57
62	Study on wear properties of aluminiumâ€“silicon piston alloy. Journal of Materials Processing Technology, 2001, 118, 69-73.	3.1	129